ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SOIC 14-28 LEAD					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
85/85	55	55,000	85°C, 85%RH	0	0.00
BOND INT	720	400,000	200°C + N2	0	0.00
HAST	3,220	344,000	130°C, 85%RH	0	0.00
HIGH TEMP STORAGE	328	55,104	200°C	0	0.00
Pressure Pot	8,596	835,216	121°, 15 PSIG	0	0.00
Solder DUNK	765	2,295	260°C, 10SEC	0	0.00
Solderability	1,955	17,000	883 M2003	0	0.00
Temp Cycle	10,927	3,682,500	−65°C−150°C	0	0.00
Thermal Shock	200	20,000	−60°C−150°C	0	0.00